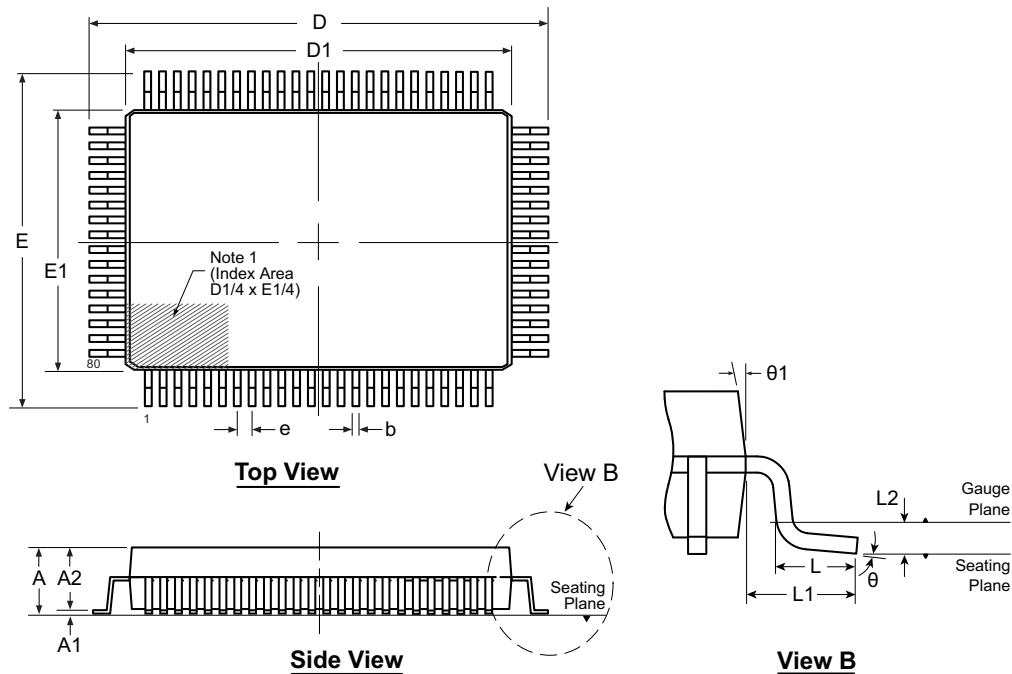


80-Lead PQFP Package Outline (PG)

20.00x14.00mm body, 3.40mm height (max), 0.80mm pitch, 3.90mm footprint



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Note:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol		A	A1	A2	b	D	D1	E	E1	e	L	L1	L2	θ	θ1
Dimension (mm)	MIN	2.80*	0.25	2.55	0.30	23.65*	19.80*	17.65*	13.80*	0.80 BSC	0.73	1.95 REF	0.25 BSC	0°	5°
	NOM	-	-	2.80	-	23.90	20.00	17.90	14.00		0.88			3.5°	-
	MAX	3.40	0.50*	3.05	0.45	24.15*	20.20*	18.15*	14.20*		1.03			7°	16°

JEDEC Registration MO-112, Variation CB-1, Issue B, Sept. 1995.

* This dimension is not specified in the JEDEC drawing.

Drawings not to scale.